

# MDA251P75SBPG1

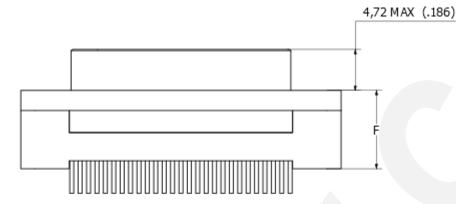
## **General information**

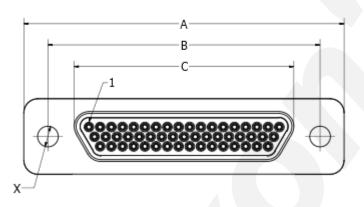
- § Rectangular micro-D connector
- § Nickel aluminium shell + potting 150°C
- § PCB Vertical mount with pitch 0,075" board straight specific layout
- § Male (pin contacts) : 51 contacts
- § Gold plated solid conductor AWG 25 (MicroD) or AWG 30 (NanoD) : 2.80 mm (0.110")
- § Jackposts (removable)

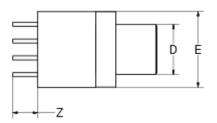
# Dimensions

Dimensions are in millimetres (inches)









A max.	B ± 0.13 (±.005)	C max. Male	C max. Female	D max. Male	D max. Female	E max.	F max.	x	Z ±0.38 (±.015)
36.45	30.86	24.99	26.70	5.79	7.44	10.16	9.02	2.24/2.44	2.80
(1.435)	(1.215)	(.984)	(1.051)	(.228)	(.293)	(.400)	(.355)	(-)	(.110)

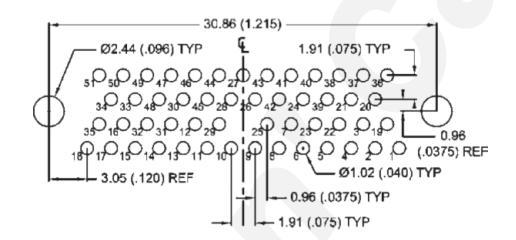
All the drawings are not at scale.



#### Summary of characteristics

ELECTRICAL & MECHA	NICAL PERFORMANCE	MATERIAL & FINISH		
CURRENT RATING	3 A max.	SHELL	Aluminium alloy 6061 or 300 series stainless steel, see ordering info for plating options	
CONTACT RESISTANCE	8 mΩ max.	MOULDED INSULATOR	Liquid Crystal Polymer (LCP)	
INSULATION RESISTANCE	5000 MΩ min. @ 500 V AC	INTERFACIAL SEAL	Fluorosilicone rubber	
DIELECTRIC WITHSTANDING VOLTAGE	Sea level : 600V AC Altitude 21km (70,000 ft) : 150V AC	PIN CONTACT	Copper and berryllium copper, gold over nickel plating	
CONTACT ENGAGING FORCE	170 g max. (6 oz)	SOCKET CONTACT	Copper alloy, gold over nickel plating	
CONTACT SEPARATING FORCE	14 g min. (0,5 oz)	ENCAPSULANT	Epoxy resin	
CONTACT RETENTION	2,26 kg (5 lbs)	MOULDED TRAY	Liquid Crystal Polymer (LCP)	
DURABILITY	500 mating cycles min.	PCB TERMINALS	See ordering info for PCB terminals material	
VIBRATION	20g's - No Discontinuity > 1µs	HARDWARE	300 series stainless steel, passivated	
SHOCK	50g's - No Discontinuity > 1µs			

## **PCB Layout**



All the drawings are not at scale.



#### Hardware

